

# Switching Diode

## BAS16M3T5G

### Features

- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS

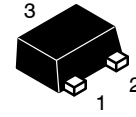
Rating	Symbol	Value	Unit
Continuous Reverse Voltage	$V_R$	100	Vdc
Peak Forward Current	$I_F$	200	mAdc
Peak Forward Surge Current	$I_{FM(surge)}$	500	mAdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

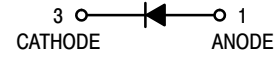
### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, FR-4 Board (Note 1) $T_A = 25^\circ\text{C}$ Derated above $25^\circ\text{C}$	$P_D$	260	mW
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	490	$^\circ\text{C/W}$
Total Device Dissipation, FR-4 Board (Note 2) $T_A = 25^\circ\text{C}$ Derated above $25^\circ\text{C}$	$P_D$	580	mW
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	215	$^\circ\text{C/W}$
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

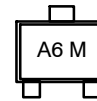
1. FR-4 @ Minimum Pad
2. FR-4 @ 1.0 × 1.0 Inch Pad



SOT-723  
CASE 631AA  
STYLE 2



### MARKING DIAGRAM



A6 = Specific Device Code  
M = Date Code

### ORDERING INFORMATION

Device	Package	Shipping†
BAS16M3T5G	SOT-723 (Pb-Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

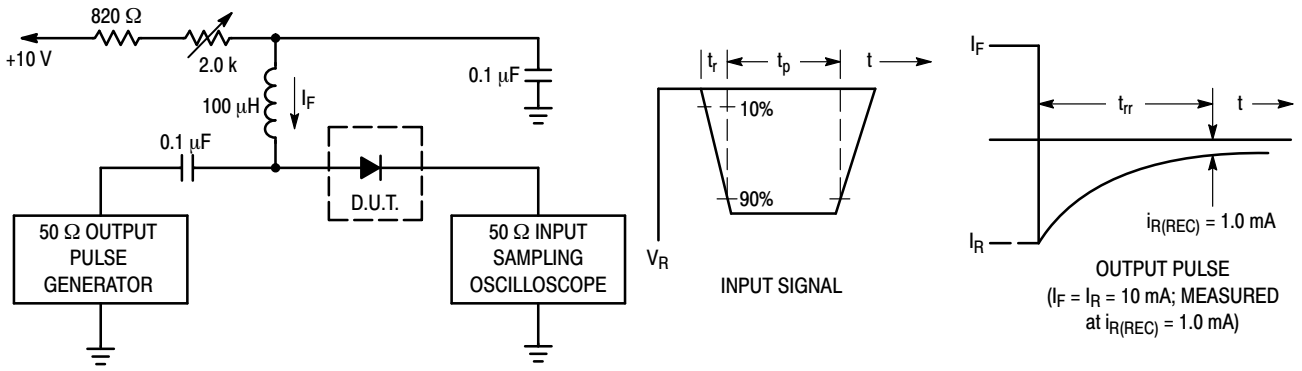
# BAS16M3T5G

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Reverse Voltage Leakage Current (V <sub>R</sub> = 100 Vdc) (V <sub>R</sub> = 75 Vdc, T <sub>J</sub> = 150°C) (V <sub>R</sub> = 25 Vdc, T <sub>J</sub> = 150°C)	I <sub>R</sub>	–	1.0 50 30	μA <sub>dc</sub>
Reverse Breakdown Voltage (I <sub>BR</sub> = 100 μA <sub>dc</sub> )	V <sub>(BR)</sub>	100	–	V <sub>dc</sub>
Forward Voltage (I <sub>F</sub> = 1.0 mA <sub>dc</sub> ) (I <sub>F</sub> = 10 mA <sub>dc</sub> ) (I <sub>F</sub> = 50 mA <sub>dc</sub> ) (I <sub>F</sub> = 150 mA <sub>dc</sub> )	V <sub>F</sub>	–	715 855 1000 1250	mV
Diode Capacitance (V <sub>R</sub> = 0, f = 1.0 MHz)	C <sub>D</sub>	–	2.0	pF
Forward Recovery Voltage (I <sub>F</sub> = 10 mA <sub>dc</sub> , t <sub>r</sub> = 20 ns)	V <sub>FR</sub>	–	1.75	V <sub>dc</sub>
Reverse Recovery Time (I <sub>F</sub> = I <sub>R</sub> = 10 mA <sub>dc</sub> , R <sub>L</sub> = 50 Ω)	t <sub>rr</sub>	–	6.0	ns
Stored Charge (I <sub>F</sub> = 10 mA <sub>dc</sub> to V <sub>R</sub> = 5.0 V <sub>dc</sub> , R <sub>L</sub> = 500 Ω)	Q <sub>S</sub>	–	45	pC

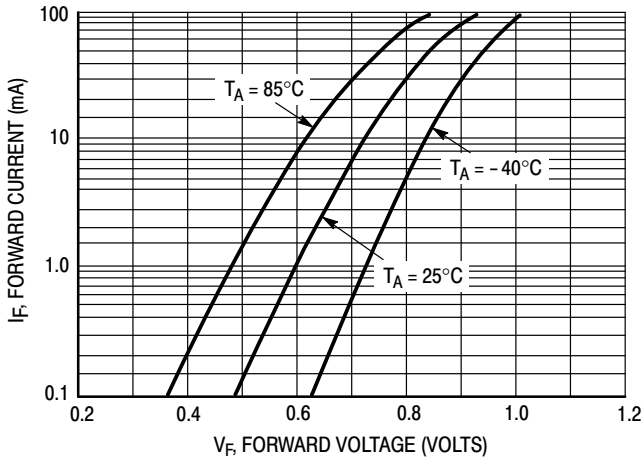
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# BAS16M3T5G

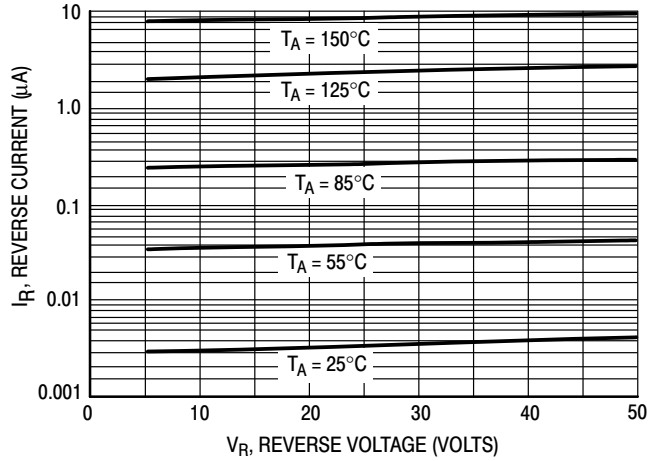


- Notes: 1. A 2.0 kΩ variable resistor adjusted for a Forward Current ( $I_F$ ) of 10 mA.  
 2. Input pulse is adjusted so  $I_{R(\text{peak})}$  is equal to 10 mA.  
 3.  $t_p > t_{rr}$

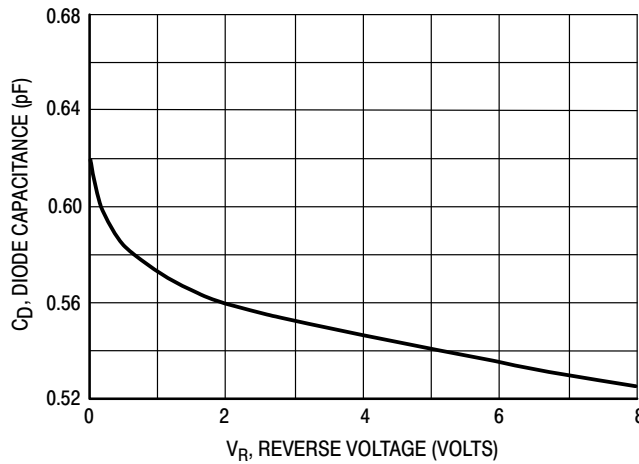
**Figure 1. Recovery Time Equivalent Test Circuit**



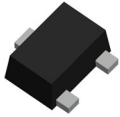
**Figure 2. Forward Voltage**



**Figure 3. Leakage Current**



**Figure 4. Capacitance**



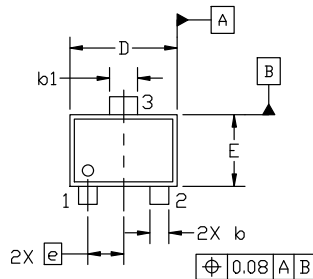
**SOT-723 1.20x0.80x0.50, 0.40P**  
**CASE 631AA**  
**ISSUE E**

DATE 24 JAN 2024

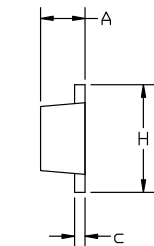
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

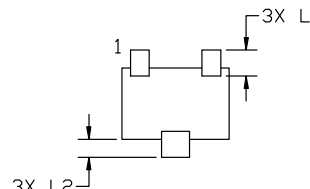
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.45	0.50	0.55
b	0.15	0.21	0.27
b1	0.25	0.31	0.37
c	0.07	0.12	0.17
D	1.15	1.20	1.25
E	0.75	0.80	0.85
e	0.40 BSC		
H	1.15	1.20	1.25
L	0.29 REF		
L2	0.15	0.20	0.25



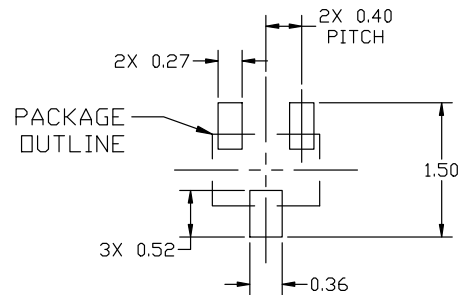
TOP VIEW



SIDE VIEW



BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT

**GENERIC MARKING DIAGRAM\***



XX = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:	STYLE 5:
PIN 1. BASE	PIN 1. ANODE	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. GATE
2. EMITTER	2. N/C	2. ANODE	2. CATHODE	2. SOURCE
3. COLLECTOR	3. CATHODE	3. CATHODE	3. ANODE	3. DRAIN

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<b>DESCRIPTION:</b>	<b>SOT-723 1.20x0.80x0.50, 0.40P</b>	<b>PAGE 1 OF 1</b>

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